CURRENT DATE: 8-APRIL-2014

PRODUCT CHANGE NOTIFICATION

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TE CONNECTIVITY

CUSTOMER: HEILIND ELECTRONICS PRODUCT CHANGE NOTIFICATION NO: E-14-002835

LOCATION: WILMINGTON PCN DATE: 07-APR-14

CUSTOMER NO: 167811 AGREEMENT NO:

TE CONNECTIVITY ENTITY: RMP (1082) - U.S. Operations on SAP

We would like to inform you about the following change(s) to the listed TE Connectivity Product. In case of any further questions about this change(s), please contact your TE Connectivity Sales Engineer. Affected part, drawing and/or specification numbers are listed on the attached sheet(s).

GENERAL PRODUCT DESCRIPTION:

AMPMODU II Breakaway Pin Headers (0.63mm Square Post)

DESCRIPTION OF CHANGE:

Contact pin base material change from CuSn (Phosphor bronze)to CuZn (Brass). Plating change from min. 0.8microns gold plating to min. 0.7 microns Pd Ni + 0.1 microns gold flash at contact area (Area F).

REASON FOR CHANGE:

Product Improvement. Streamlining of contact base material. Plating process transfer to TE Bydgoszcz. To maintain a competitive position in the market place. Product tested and validated see test report 502-19945.

ESTIMATE DATE:

LAST ORDER DATE:

(OBSOLETE PARTS ONLY)

LAST SHIP DATE:

(OBSOLETE PARTS ONLY)

FIRST DATE TO SHIP CHANGED PARTS:

10-JUL-2014

(CHANGED PARTS ONLY)

LAST DATE FOR MIXED

SHIPMENTS: NO MIXED SHIPMENTS

(CHANGED PARTS ONLY)

1 of 2

CURRENT DATE: 8-APRIL-2014

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PARTS BEING MODIFIED CUSTOMER PART NBR

1-826652-0

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